2SD1268

Silicon NPN epitaxial planar type

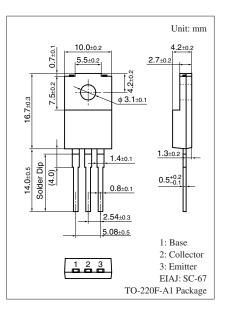
For power switching

Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- \bullet Satisfactory linearity of forward current transfer ratio h_{FE}
- \bullet Large collector current I_{C}
- Full-pack package which can be installed to the heat sink with one screw.

3 C					
Parameter	Symbol	Rating	Unit		
Collector-base voltage (Er	V _{CBO}	130	V		
Collector-emitter voltage (V _{CEO}	80	V		
Emitter-base voltage (Coll	V _{EBO}	7	V		
Collector current	I _C	3	А		
Peak collector current	I _{CP}	6	А		
Collector power	P _C	30	W		
dissipation	$T_a = 25^{\circ}C$		2.0		
Junction temperature	Tj	150	°C		
Storage temperature	T _{stg}	-55 to +150	°C		





Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

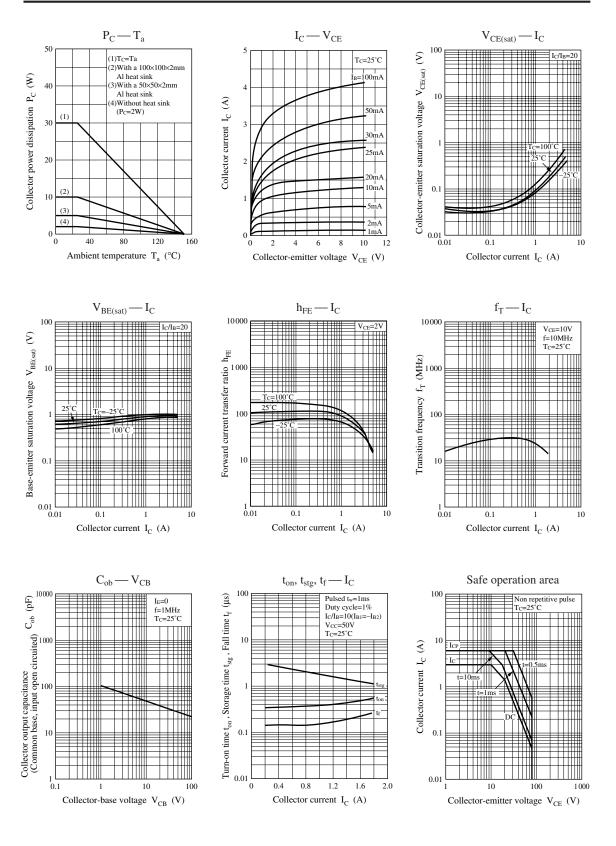
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0$	80			V
Collector-base cut-off current (Emitter open)	I _{CBO}	$V_{CB} = 100 \text{ V}, I_E = 0$			10	μΑ
Emitter-base cut-off current (Collector open)	I _{EBO}	$V_{EB} = 5 V, I_C = 0$			50	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = 2 V, I_C = 0.1 A$	45			
	h _{FE2} *	$V_{CE} = 2 V, I_C = 0.5 A$	60		260	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 2 \text{ A}, I_{\rm B} = 0.1 \text{ A}$			0.5	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{\rm C} = 2 \text{ A}, I_{\rm B} = 0.1 \text{ A}$			1.5	V
Transition frequency	f _T	$V_{CE} = 10 \text{ V}, I_C = 0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t _{on}	$I_{C} = 0.5 \text{ A}, I_{B1} = 50 \text{ mA}, I_{B2} = -50 \text{ mA}$		0.5		μs
Storage time	t _{stg}	$V_{CC} = 50 V$		2.5		μs
Fall time	t _f			0.15		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2.	*:	Rank	classificati	on

Rank	R	Q	Р	
h _{FE2}	60 to 120	90 to 180	130 to 260	

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